

Call for Papers

iMAPS New England – 43rd Symposium & Expo

**The Largest Regional Symposium Dedicated to
Microelectronics and Packaging**



The New England Chapter

May 3, 2016

**Holiday Inn – Boxborough Conference Center
Boxborough, Massachusetts**

- RF Microwave Materials and Processes
- Copper Wirebonding
- Surface Mount Technology
- Thermal Management
- Military and Defense Electronics
- Advanced Packaging 2.5/3D and TSV
- Medical Devices
- High Temp Electronics
- Automotive & Consumer Applications
- Near Hermetic Packaging
- MEMS Sensors and Nano Technology
- Printed Electronics
- Optoelectronics
- Emerging Technologies

**Symposium Technical Chair
Dmitry Marchenko, Microsemi**

**Please e-mail your 250 word abstract to:
dmitry.marchenko@live.com**

Deadline for Submission – December 31, 2015

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